

PRODUCT CHARACTERISTICS

V_{DSS}	650V
$R_{DS(ON)}$ Typ(@ $V_{GS}=10V$)	32m Ω
Qg@typ	167.3nC
I_D	84A

APPLICATIONS

- * High efficiency switch mode power supplies
- * Electronic lamp ballasts based on half bridge
- * LED power supplies

FEATURE

- * High Switching Speed
- * Improved dv/dt capability

ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT65R040N	TO-247	30 pieces/Tube

ABSOLUTE MAXIMUM RATINGS($T_c=25^{\circ}C$, unless otherwise specified)

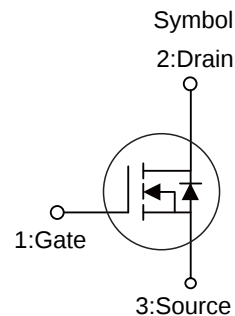
Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	650	V
Gate-Source Voltage	V_{GSS}	± 30	V
Drain Current Continuous(@ $V_{GS}=10V$, $T_c=25^{\circ}C$)	I_D	84	A
Drain Current Pulsed	I_{DM}	252	A
Avalanche Energy *	E_{AS}	1620	mJ
Power Dissipation	P_D	694	W
Junction Temperature	T_J	+150	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}C$

THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R_{thJC}	0.18	$^{\circ}C/W$
Junction-to-Ambient, minimal Footprint ¹	R_{thJA}	62	$^{\circ}C/W$

Note: * EAS condition: $T_J=25^{\circ}C$, $V_{DD}=50V$, $V_G=10V$, $L=10mH$, $R_g=25\Omega$

¹ The value of R_{thJA} is measured by placing the device in a still air box which is one cubic foot.



■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V _{DSS}	V _{GS} =0V, I _D =250μA	650	-	-	V
Drain to Source Leakage Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V	-	-	10	μA
Gate to Source Forward Leakage	I _{GSS(F)}	V _{DS} =0V, V _{GS} =+30V	-	-	100	nA
Gate to Source Reverse Leakage	I _{GSS(R)}	V _{DS} =0V, V _{GS} =-30V	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =35A	-	32	41	mΩ
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	3.0	-	5.0	V
Dynamic characteristics						
Gate capacitance	R _g	V _{GS} =0V, V _{DS} =0V ,f=1.0MHz	-	4.2	-	Ω
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =5.5 A	-	20	-	S
Input Capacitance	C _{iss}	V _{DS} =100V, V _{GS} =0V f=250kHz	-	8513	-	pF
Output Capacitance	C _{oss}		-	275	-	pF
Reverse Transfer Capacitance	C _{rss}		-	4.6	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	t _{d(ON)}	I _D =35 A, V _{DS} =400V R _G =10Ω ,V _{GS} =10V	-	293.6	-	ns
Rise Time	t _r		-	31.7	-	ns
Turn-off Delay Time	t _{d(OFF)}		-	258.6	-	ns
Fall Time	t _f		-	8.6	-	ns
Total Gate Charge	Q _g	I _D =35 A, V _{DS} =520V V _{GS} =10V	-	167.3	-	nC
Gate to Source Charge	Q _{gs}		-	49.1	-	nC
Gate to Drain("Miller") Charge	Q _{gd}		-	62.9	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I _s		-	-	84	A
Maximum Pulsed Current(Body Diode)	I _{SM}		-	-	252	A
Diode Forward Voltage	V _{SD}	I _{SD} =35 A, V _{GS} =0V	-	0.83	1.2	V
Reverse Recovery Time	t _{rr}	V _{DS} =400V, I _D =35A,	-	194.5	-	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt=100 A/μs	-	1916.3	-	nC

Electrical Characteristics Diagrams

Fig 1: Output Characteristics

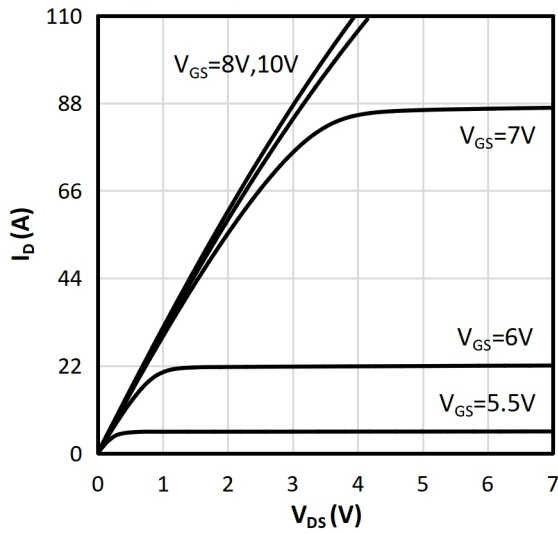


Fig 2: Transfer Characteristics

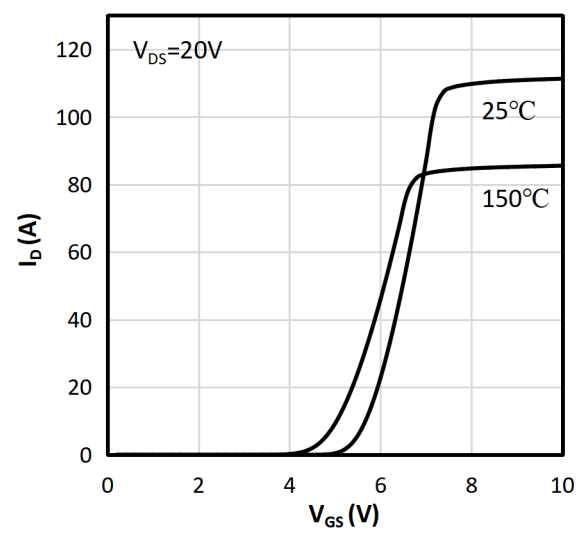


Fig 3: $R_{DS(on)}$ vs Drain Current

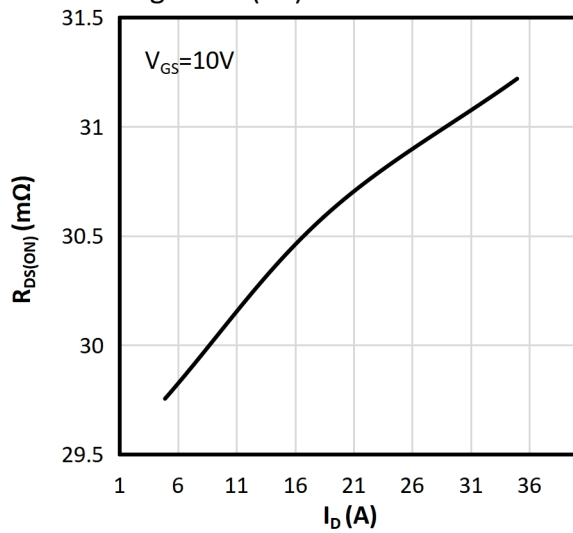


Fig 4: $R_{DS(on)}$ vs. Temperature

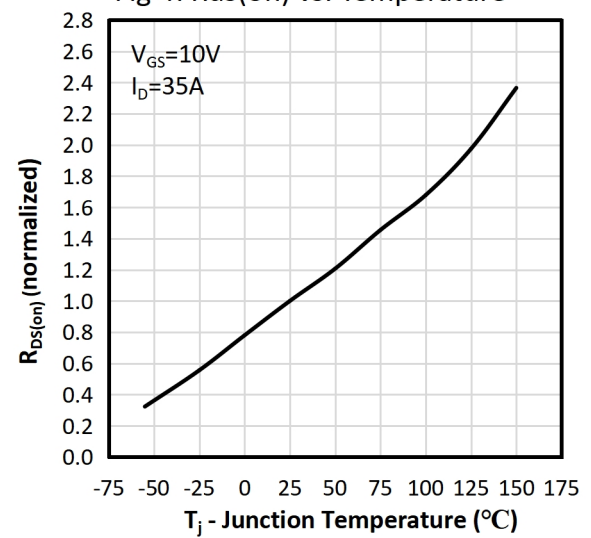


Fig 5: Breakdown Voltage vs. Temperature

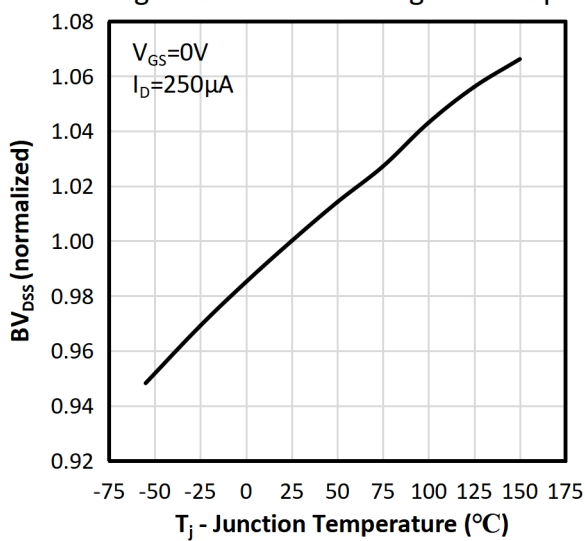


Fig 6: Threshold voltage vs. Temperature

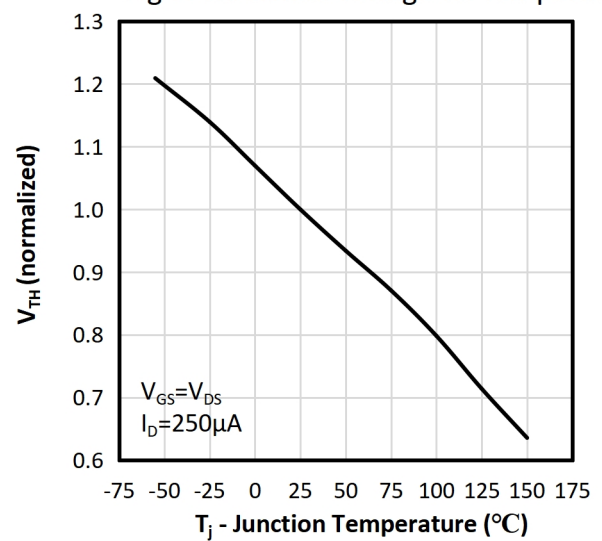


Fig 7: Body-Diode Characteristics

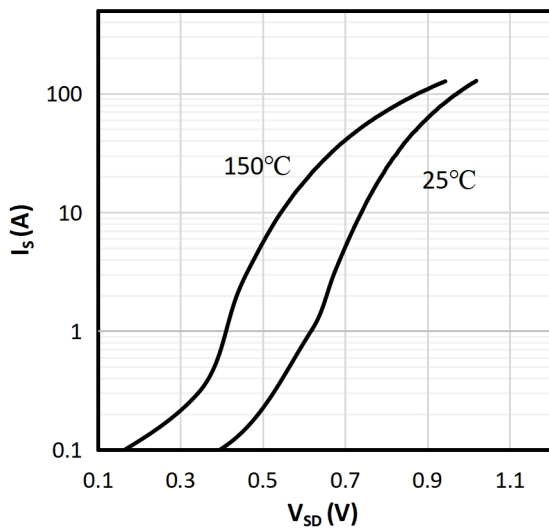


Fig 8: Capacitance Characteristics

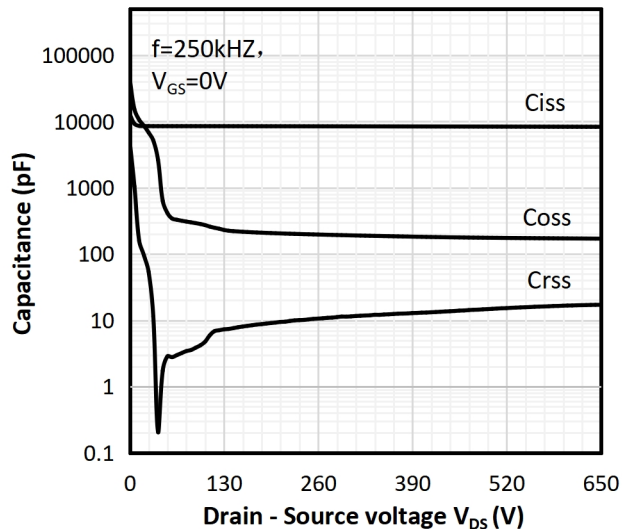


Fig 9: Gate charger Characteristics

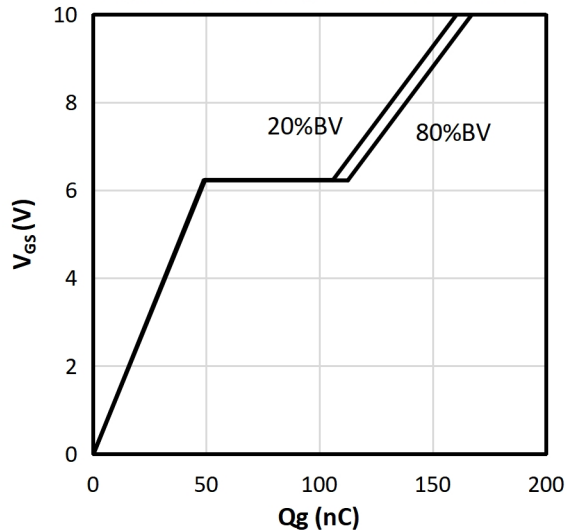


Fig 10: Drain Current Derating

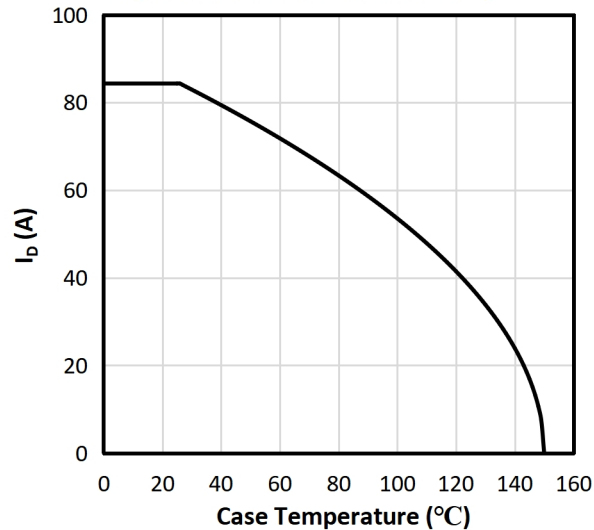


Fig 11: Power Dissipation vs. Temperature

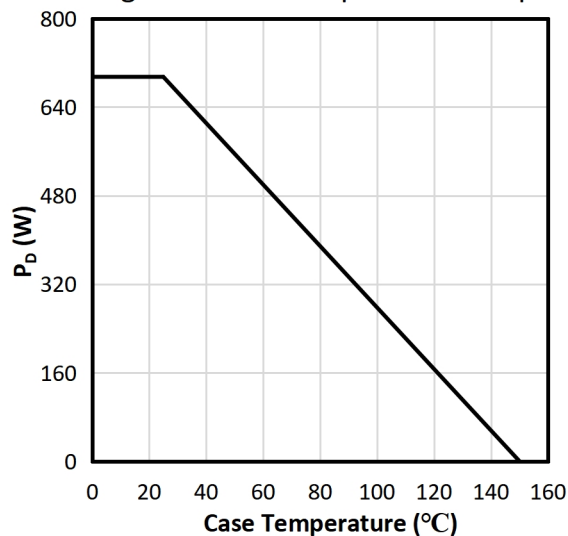
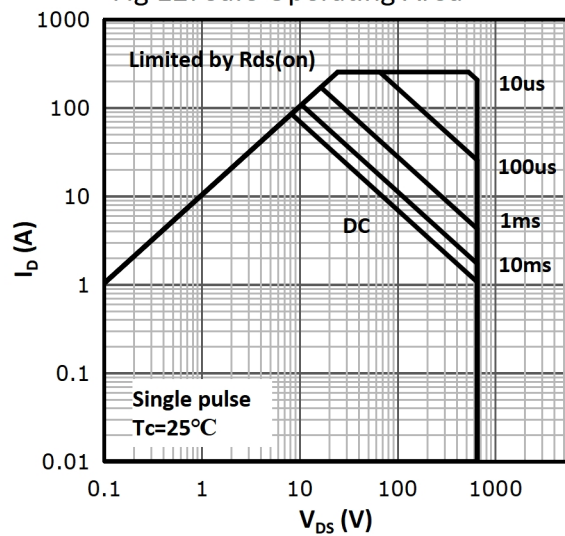


Fig 12: Safe Operating Area



■ TO-247 PACKAGE OUTLINE DIMENSIONS

